

(0.635 mm) .025"

# **MIXED TECHNOLOGY SOCKET**

### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

**Insulator Material:** Liquid Crystal Polymer Contact Material: **Phosphor Bronze** Plating: Au or Sn over 50 µ" (1.27 µm) Ni Operating Temp Range: -55 °C to +125 °C Voltage Rating: 275 VAC Max Cycles: RoHS Compliant:

#### **PROCESSING**

Lead-Free Solderable: SMT Lead Coplanarity: (0.10 mm) .004" max (019-057) **Board Stacking:** 

For applications requiring more than two connectors per board contact ipg@samtec.com

### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality

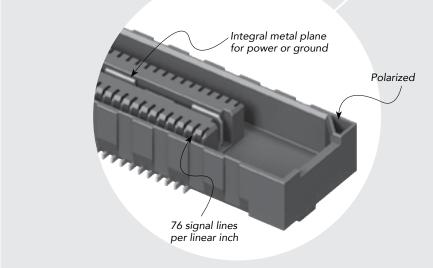


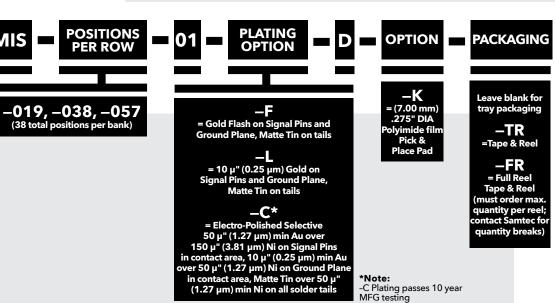
## **ALSO AVAILABLE** (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 µ" (0.76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

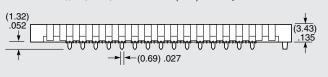
**Board Mates:** 

Standoffs:





(No. of Positions/19) x (12.70) .500 + (12.70) .500 (12.70) .500 <del>,,,,,,,,,,,,,,,,,,,,,</del> (6.22) .245 -(0.635) .025 (0.15) .006→



**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

**MATED HEIGHT\*** MIT LEAD STYLE -01 | -02 (5.00) (8.00) -01 .197 .315

(3.63)

\*Processing conditions will affect mated height. See SO Series for board space tolerances.

Some lengths, styles and options are non-standard, non-returnable.